

RECEIVED
CENTRAL FAX CENTER

Serial No. 10/757,131

AUG 19 2005

PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

DIANA, Daniel et al.

Group Art Unit: 2823

T. D

Serial No.: 10/747,824

Examiner: DANG, Trung Q.

8/26/05

Filed: December 29, 2003

Atty. Docket #: INTEL16

Title: METHOD AND APPARATUS FOR
FILLING INTERLAYER VIAS ON
FERROELECTRIC POLYMER
SUBSTRATES

Assignee: Intel Corporation

AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This submission is in response to the Final Official Action mailed by the U.S. Patent and Trademark Office on June 16, 2005. As of this Official Action, pending claims 1 - 9, and 22 - 25 are allowed, claims 13 - 15 stand rejected, and claims 16, 17, and 19 - 21 are objected to. In response to this Final Official Action, it is respectfully requested that the Office consider the following remarks and amendments to the above-referenced application.